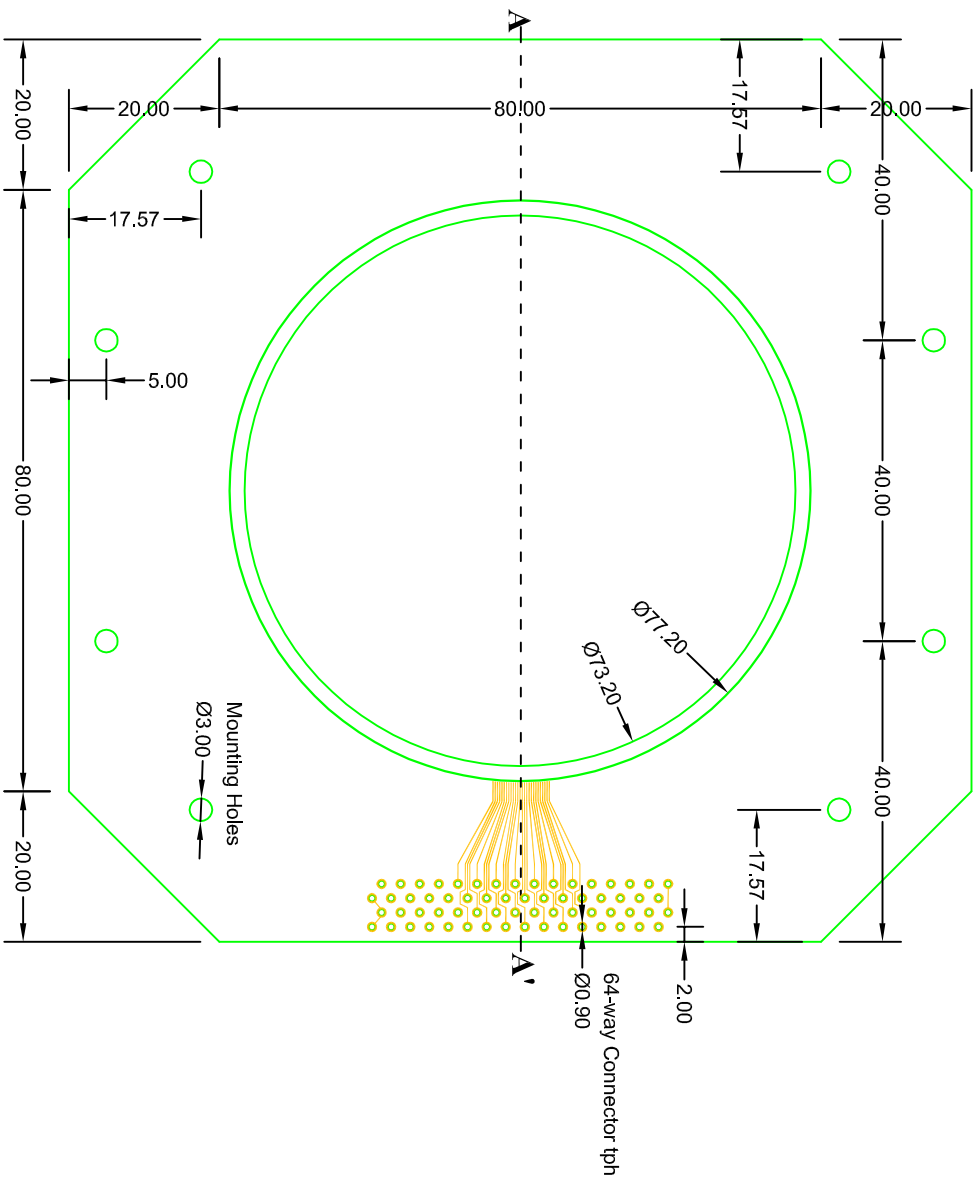
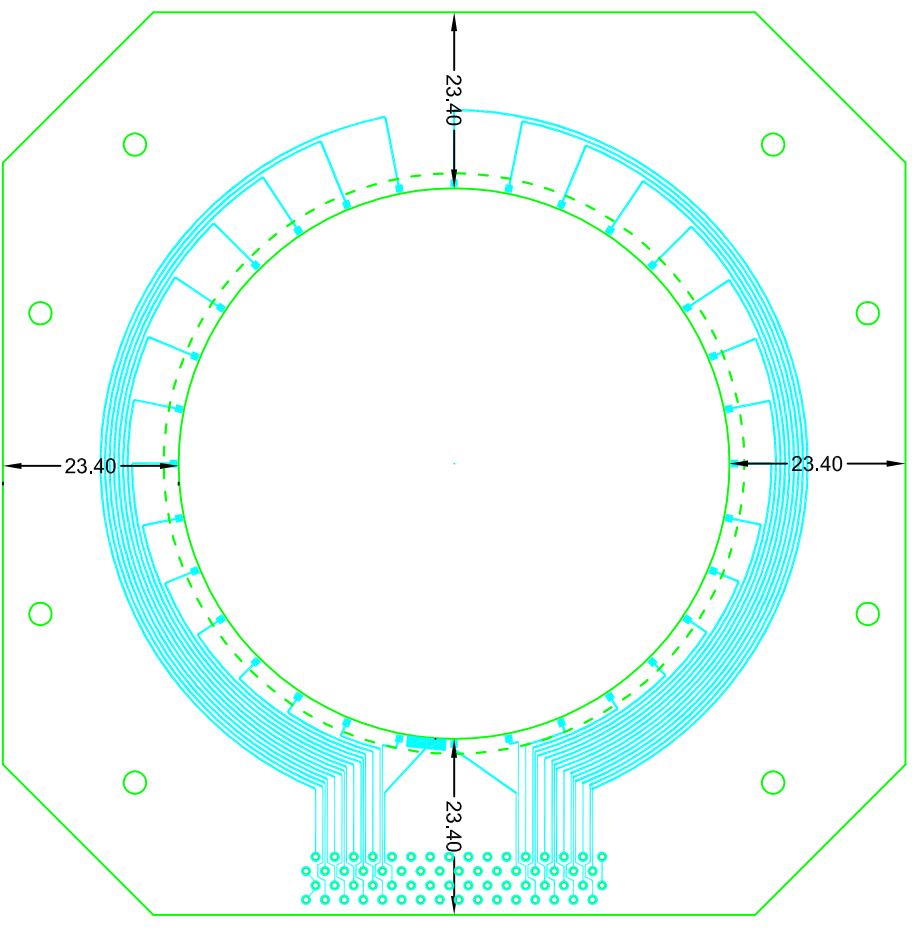


PCB Junction Side Viewed from the Front.



PCB Ohmic Side Viewed Through the Junction Side.



PCB Cross Section AA'.



CHIP DIAMETER = 76000 um

Key

-  PCB
-  Front Tracking
-  Rear Tracking

Drawn: Checked	Date	Tolerances Unless Stated			
S.W./AN	04/06/2007	Package O/D ± 0.1mm	Material - Standard FR4 2.40 mm Total Thickness	Plating - Soft Au on 1 oz Cu	
Design Approved		Package Hole Ø ± 0.05mm	Package Hole Pos'n ± 0.1mm	Solder Resist Front - N/A	Front Coverlay - N/A
			Material Thickness ± 0.1	Solder Resist Rear - N/A	Rear Coverlay - N/A
				Ledge - 1.4 mm from Top Surface	

Title.

S3 PCB Design.

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Scale: 1:1 Dims In. mm Drg. No. A-3329

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